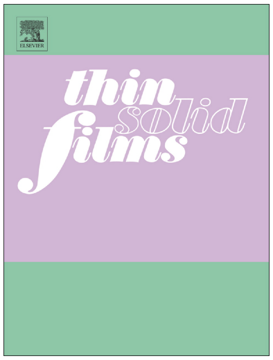

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Microstructure and mechanical properties of metastable solid solution copper-tungsten films

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